

Material Composition Specification

SOIC-16 Case

Available with Pb(lead)-free plating*



Device average mass145 mg
Fluctuation margin +/-10%

Device part	Substance	mass (mg)
active device	doped Si	3.86
bond wire	Au	0.40
leadframe	Cu alloy	45.50
Die attach	Silver epoxy - Ag 80% - epoxy resin 20%	0.44
*plating	SnPb15 or Sn (100% tin, Pb-free)	2.30 2.30
encapsulation	partially brominated epoxy -silica -resin < 25% -Sb ₂ O ₃ < 2.0% -TBBA < 2.5% -carbon < 0.5%	92.50

* specify Lead-free when ordering 100% tin (Pb-free) plating option.